TOSHIBA Photocoupler GaAlAs Ired & Photo IC

6N138, 6N139

Current Loop Driver Low Input Current Line Receiver CMOS Logic Interface

The TOSHIBA 6N138 and 6N139 consists of a GaAlAs infrared emitting diode coupled with a split-Darlington output configuration.

A high speed GaAlAs Ired manufactured with an unique LPE junction, has the virtue of fast rise and fall time at low drive current.

- Isolation voltage: 2500 Vrms (min)
- · Current transfer ratio

: 6N138 - 300% (min) (I_F=1.6mA)

: 6N139 - 400% (min) (I_F=0.5mA)

Switching time: 6N138 - t_{PHL} = 10µs (max)

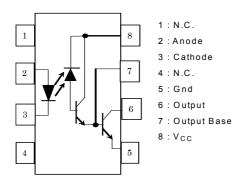
- t_{PLH} = 35 μ s (max)

 $6N139 - t_{PHL} = 1 \mu s (max)$

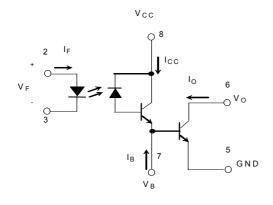
 $-t_{PLH} = 7\mu s (max)$

UL recognized: UL1577, file no. E67349

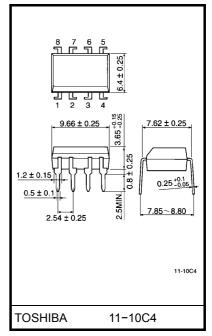
Pin Configuration (top view)



Schematic



Unit: mm



Weight: 0.54 g (typ.)

Absolute Maximum Ratings (*) (Ta = 0°C to + 70°C)

Characteristic			Symbol	Rating	Unit	
	Forward current	(Note 1)	lF	20	mA	
	Pulse forward current		I _{FP} (*1)	40	mA	
E	Total pulse forward current		I _{FP} (*2)	1	А	
	Reverse voltage		V _R	5	V	
	Diode power dissipation	(Note 2)	P _D	35	mW	
	Output current	(Note 3)	IO	60	mA	
or	Emitter-base reverse voltage		V_{EB}	0.5	V	
Detector	Supply voltage		V _{CC} ^(*3)	–0.5 to 18	V	
ă	Output voltage		VO ^(*3)	–0.5 to 18	V	
	Output power dissipation	(Note 4)	PO	100	mW	
Оре	Operating temperature range		T _{opr}	0 to 70	°C	
Sto	Storage temperature range		T _{stg}	-55 to 125	°C	
Lea	Lead solder temperature (10s) (*4)		T _{sol}	260	°C	
Inclation voltage (Aminute D.I. < 600/)			BV _S (**)	2500	V _{rms}	
Isolation voltage (1minute, R.H.≤ 60%)		DVS	3540	V _{dc}		

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

- (*) JEDEC registered data
- (**) Not registered JEDEC
- (*1) 50% duty cycle, 1ms pulse width
- (*2) Pulse width 1µs, 300pps
- (*3) 6N138··· -0.5 to 7V
- (*4) 1.6mm below seating plane

Electrical Characteristics Over Recommended Temperature (Ta = 0°C to 70°C, unless otherwise noted)

Characteristic		Symbol	Test Condition	Min	(*5)Typ.	Max	Unit
Current transfer	6N139	CTR(*)	I _F =0.5mA, V _O =0.4V V _{CC} =4.5V	400	800	_	- %
ratio (Note 5, 6)			I _F =1.6mA, V _O =0.4V V _{CC} =4.5V	500	900	_	
	6N138			300	600	_	
	6N139	V _{OL}	I _F =1.6mA, I _O =6.4mA V _{CC} =4.5V	_	0.1	0.4	- V
Logic low output			I _F =5mA, I _O =15mA V _{CC} =4.5V	_	0.1	0.4	
voltage (Note 6)			I _F =12mA, I _O =24mA V _{CC} =4.5V	_	0.2	0.4	
	6N138		I _F =1.6mA, I _O =4.8mA V _{CC} =4.5V	_	0.1	0.4	
Logic high output	6N139	I _{OH} (*)	I _F =0mA, V _O =V _{CC} =18V	_	0.05	100	μΑ
current (Note 6)	6N138		I _F =0mA, V _O =V _{CC} =7V	_	0.05	250	
Logic low supply current	(Note 6)	ICCL	I _F =1.6mA, V _O =Open V _{CC} =5V	_	0.2	_	mA
Logic high supply current (Note 6)		Іссн	I _F =0mA, V _O =Open, V _{CC} =5V	_	10		nA
Input forward voltage		V _F (*)	I _F =1.6mA, Ta=25°C	_	1.65	1.7	٧
Input reverse breakdown voltage		BV _R (*)	I _R =10μA, Ta=25°C	5	_	_	V
Temperature coefficient of forward	l voltage	ΔV _F / ΔTa	I _F =1.6mA	_	-1.9	_	mV / °C
Input capacitance		C _{IN}	f=1MHz, V _F =0	_	60	_	pF
Resistance (input-output)		R _{I-O}	V _{I-O} =500V (Note 7), R.H.≤ 60%	_	10 ¹²	_	Ω
Capacitance (input-output)		C _{I-O}	f=1MHz (Note 7)	_	0.6	_	pF

^(**) JEDEC registered data.

^(*5) All typical values are at Ta=25 $^{\circ}$ C and V_{CC}=5V, unless otherwise noted.

Switching Specifications (Ta=25°C, V_{CC}=5V, unless otherwise specified)

Characteristic		Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Propagation delay	6N139	t _{pHL} (*)	1	I_F =0.5mA, R_L =4.7k Ω	_	5	25	μs
time to logic low				I _F =12mA, R _L =270Ω	_	0.2	1	
at output (Note 6, 8)	6N138			I _F =1.6mA, R _L =2.2kΩ	_	1	10	
Propagation delay	6N139			I_F =0.5mA, R_L =4.7k Ω	_	5	60	
time to logic high		t _{pLH} (*)	1	I _F =12mA, R _L =270Ω	_	1	7	μs
at output (Note 6, 8)	6N138			I _F =1.6mA, R _L =2.2kΩ	_	4	35	
Common mode transient immunity at logic high level output	(Note 9)	CM _H	2	I_F =0mA, R_L =2.2k Ω V_{CM} =400 V_{p-p}	_	500		V / μs
Common mode transient immunity at logic low level output (No		CML	2	I_F =1.6mA R _L =2.2k Ω V _{CM} =400V _{p-p}	_	-500		V / μs

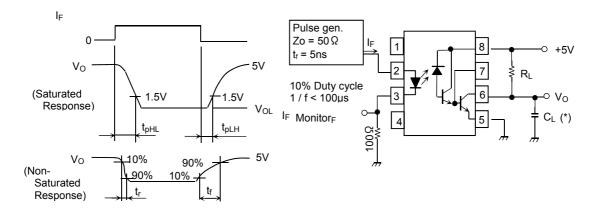
(*)JEDEC registered data.

- (Note 1): Derate linearly above 50°C free–air temperature at a rate of 0.4mA / °C
- (Note 2): Derate linearly above 50°C free–air temperature at a rate of 0.7mW / °C
- (Note 3): Derate linearly above 25°C free–air temperature at a rate of 0.7mA / °C
- (Note 4): Derate linearly above 25°C free–air temperature at a rate of 2.0mW / °C
- (Note 5): DC CURRENT TRANSFER RATIO is defined as the ratio of output collector current, I_O, to the forward LED input current, I_F, times 100%.
- (Note 6): Pin 7 open.
- (Note 7): Device considered a two–terminal device: Pins 1, 2, 3, and 4 shorted together and Pins 5, 6, 7 and 8 shorted together.
- (Note 8): Use of a resistor between pin 5 and 7 will decrease gain and delay time.
- (Note 9): Common mode transient immunity in logic high level is the maximum tolerable (positive) dV_{CM} / dt on the leading edge of the common mode pulse, V_{CM} , to assure that the output will remain in a logic high state (i.e. $V_O > 2.0V$).

4

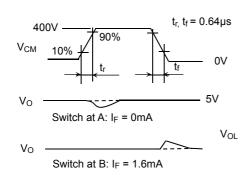
Common mode transient immunity in Logic Low level is the maximum tolerable (negative) dV_{CM} / dt on the trailing edge of the common mode pulse signal, V_{CM} , to assure that the output will remain in a logic low state (i.e. $V_O < 0.8V$).

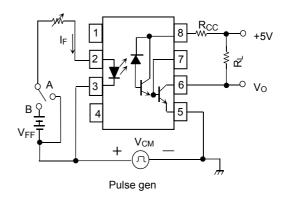
Test Circuit 1.



(*) $C_{\rm L}$ is approximately 15pF which includes probe and stray wiring capacitance.

Test Circuit 2.





5

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